NX7002BKMB

60 V, N-channel Trench MOSFET

3 December 2014 — Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 2kV HBM

3. Applications

- Relay driver
- High-speed line driver
- Low-side loadswitch
- Switching circuits

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	T_j = 25 °C		-	-	60	V
V_{GS}	gate-source voltage			-20	-	20	V
I_D	drain current	V_{GS} = 10 V; T_{amb} = 25 °C	[1]	-	-	350	mA
Static characteristics							
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 200 mA; T_j = 25 °C		-	2.2	2.8	Ω

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm^2.

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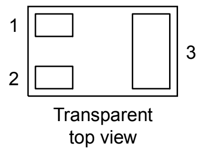
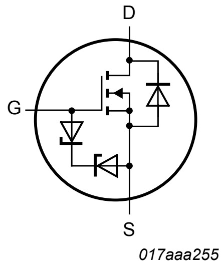
5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 DFN1006B-3 (SOT883B)	
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
NX7002BKMB	DFN1006B-3	DFN1006B-3: leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.37 mm	SOT883B

7. Marking

Table 4. Marking codes

Type number	Marking code
NX7002BKMB	0101 0111

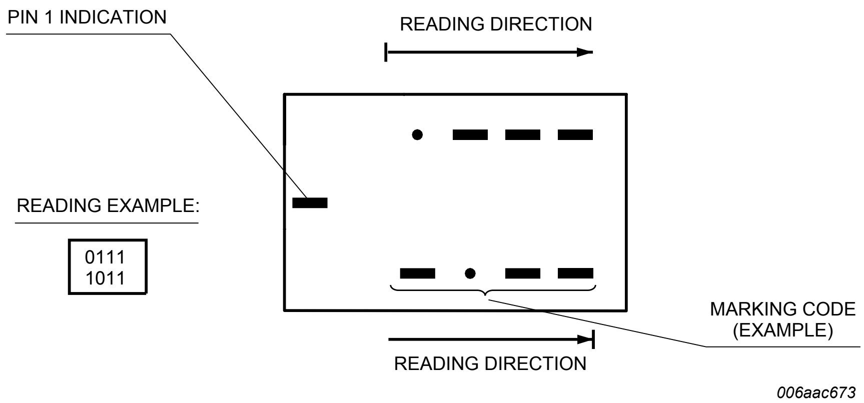


Fig. 1. DFN1006B-3 (SOT883B) binary marking code description

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	T_j = 25 °C		-	60	V
V_{GS}	gate-source voltage			-20	20	V
I_D	drain current	V_{GS} = 10 V; T_{amb} = 25 °C	[1]	-	350	mA
		V_{GS} = 10 V; T_{amb} = 100 °C	[1]	-	200	mA
I_{DM}	peak drain current	T_{amb} = 25 °C; single pulse; t_p ≤ 10 µs		-	0.9	A
P_{tot}	total power dissipation	T_{amb} = 25 °C	[2]	-	350	mW
			[1]	-	680	mW
		T_{sp} = 25 °C		-	3100	mW
T_j	junction temperature			-55	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C
Source-drain diode						
I_S	source current	T_{amb} = 25 °C	[1]	-	200	mA

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm^2.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

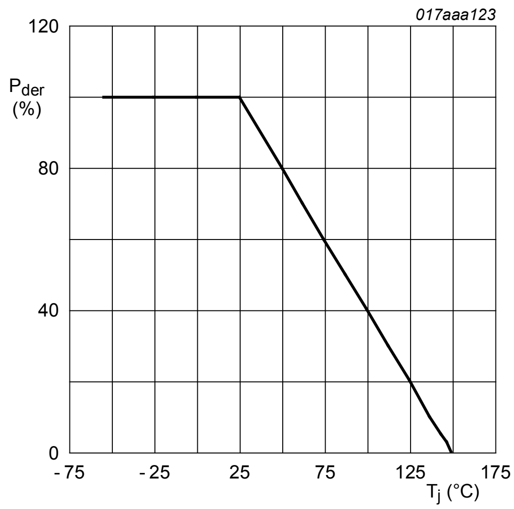


Fig. 2. Normalized total power dissipation as a function of junction temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\ \%$$

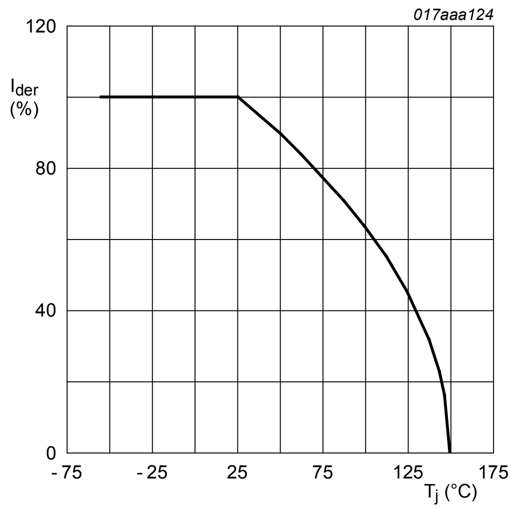
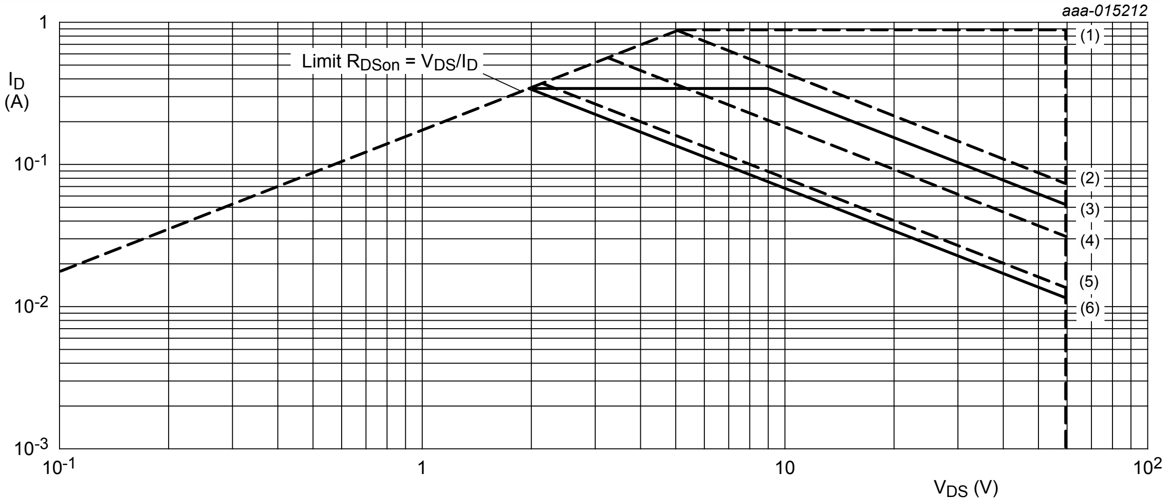


Fig. 3. Normalized continuous drain current as a function of junction temperature

$$I_{der} = \frac{I_D}{I_{D(25°C)}} \times 100\ \%$$



I_{DM} = single pulse
(1) t_p = 10 µs
(2) t_p = 1 ms
(3) DC; T_{sp} = 25 °C
(4) t_p = 10 ms
(5) t_p = 100 ms
(6) DC; T_{amb} = 25 °C; drain mounting pad 1 cm^2

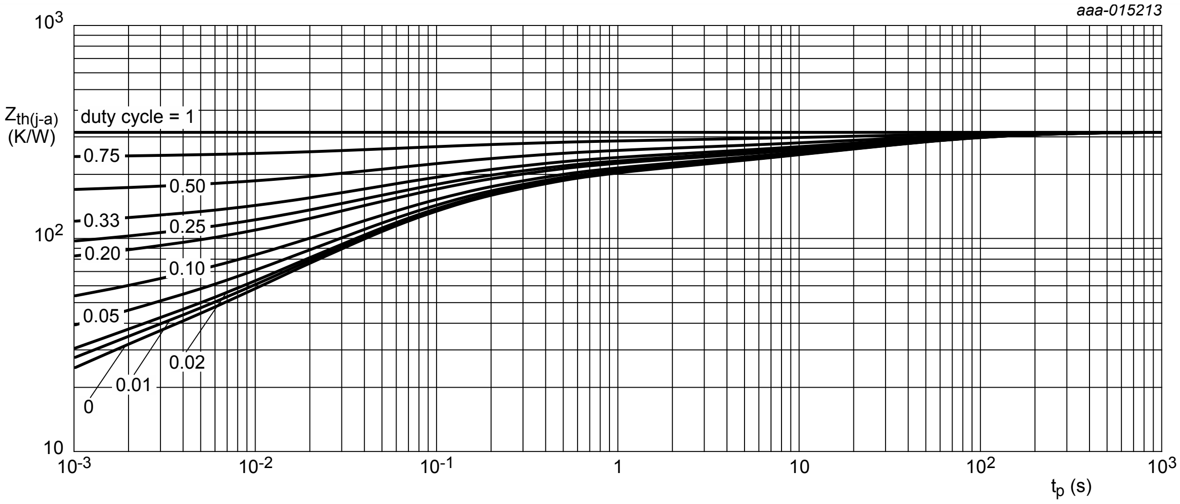
Fig. 4. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

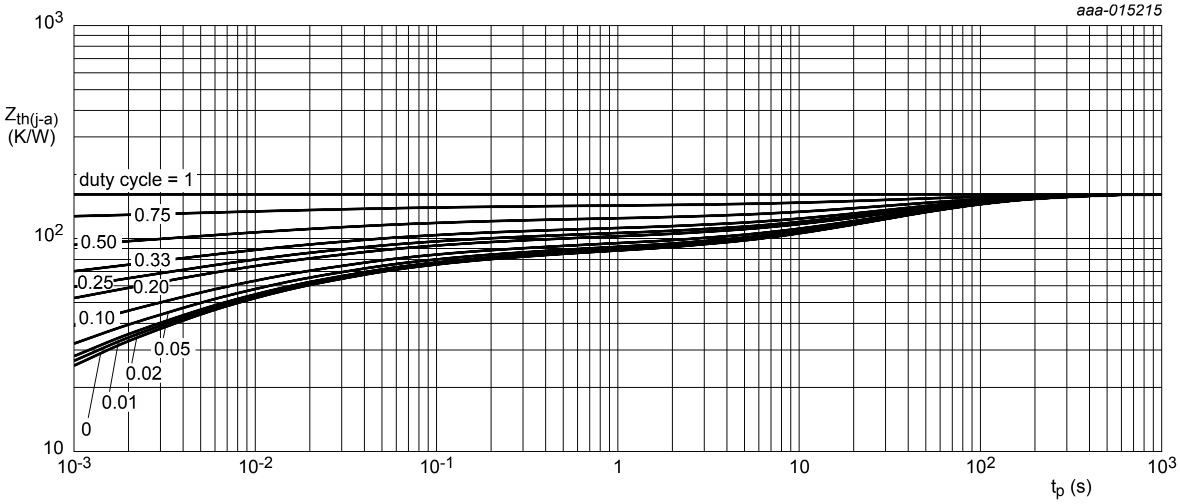
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	314	360	K/W
			[2]	-	159	180	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	35	40	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2.



FR4 PCB, standard footprint

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



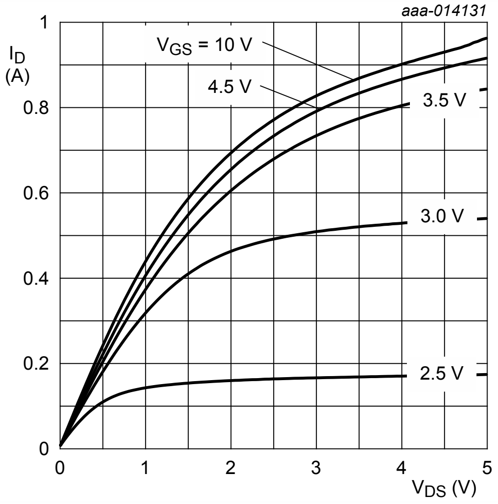
FR4 PCB, mounting pad for drain 1 cm^2

Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

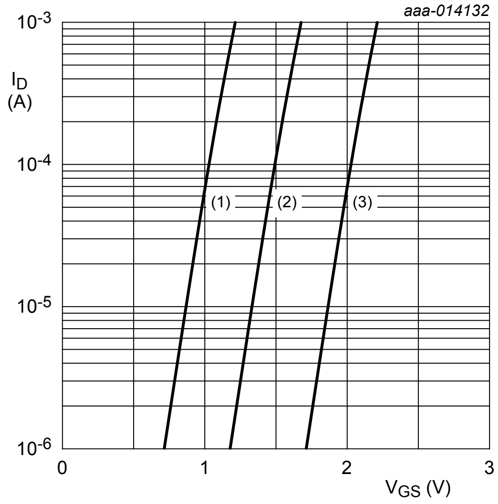
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 250 µA; V_{GS} = 0 V; T_j = 25 °C		60	-	-	V
V_{GSth}	gate-source threshold voltage	I_D = 250 µA; V_{DS} = V_{GS}; T_j = 25 °C		1.1	1.6	2.1	V
I_{DSS}	drain leakage current	V_{DS} = 60 V; V_{GS} = 0 V; T_j = 25 °C		-	-	1	µA
I_{GSS}	gate leakage current	V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 °C		-	-	10	µA
		V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C		-	-	-10	µA
		V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25 °C		-	-	1	µA
		V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25 °C		-	-	-1	µA
		V_{GS} = 5 V; V_{DS} = 0 V; T_j = 25 °C		-	-	0.3	µA
		V_{GS} = -5 V; V_{DS} = 0 V; T_j = 25 °C		-	-	-0.3	µA
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 200 mA; T_j = 25 °C		-	2.2	2.8	Ω
		V_{GS} = 10 V; I_D = 100 mA; T_j = 150 °C		-	4.5	5.7	Ω
		V_{GS} = 5 V; I_D = 200 mA; T_j = 25 °C		-	2.5	3.2	Ω
g_{fs}	forward transconductance	V_{DS} = 10 V; I_D = 200 mA; T_j = 25 °C		-	600	-	mS
R_G	internal gate resistance (AC)	f = 2.5 MHz		-	2.5	-	Ω
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	V_{DS} = 30 V; I_D = 200 mA; V_{GS} = 10 V; T_j = 25 °C		-	1	-	nC
Q_{GS}	gate-source charge			-	0.12	-	nC
Q_{GD}	gate-drain charge			-	0.18	-	nC
C_{iss}	input capacitance	V_{DS} = 10 V; f = 1 MHz; V_{GS} = 0 V; T_j = 25 °C		-	23.6	-	pF
C_{oss}	output capacitance			-	4.6	-	pF
C_{rss}	reverse transfer capacitance			-	3	-	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 50 V; I_D = 200 mA; V_{GS} = 10 V; $R_{G(ext)}$ = 6 Ω; T_j = 25 °C		-	4.7	-	ns
t_r	rise time			-	4.3	-	ns
$t_{d(off)}$	turn-off delay time			-	6.9	-	ns
t_f	fall time			-	2.9	-	ns
Source-drain diode							
V_{SD}	source-drain voltage	I_S = 200 mA; V_{GS} = 0 V; T_j = 25 °C		-	0.87	1.2	V



T_j = 25 °C

Fig. 7. Output characteristics: drain current as a function of drain-source voltage; typical values



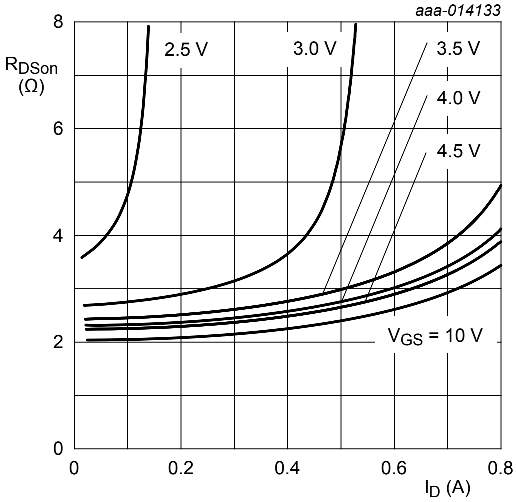
T_j = 25 °C; V_{DS} = 5 V

(1) minimum values

(2) typical values

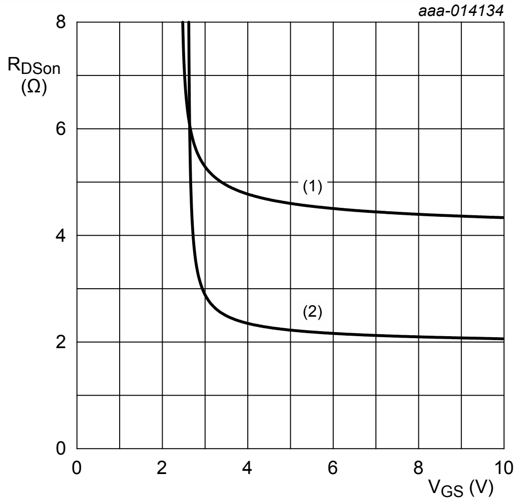
(3) maximum values

Fig. 8. Sub-threshold drain current as a function of gate-source voltage



T_j = 25 °C

Fig. 9. Drain-source on-state resistance as a function of drain current; typical values

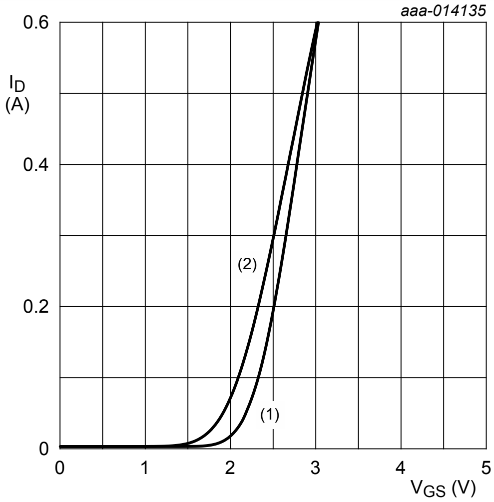


I_D = 0.2 A

(1) T_j = 150 °C

(2) T_j = 25 °C

Fig. 10. Drain-source on-state resistance as a function of gate-source voltage; typical values



$V_{DS} > I_D \times R_{DSon}$

(1) T_j = 25 °C

(2) T_j = 150 °C

Fig. 11. Transfer characteristics: drain current as a function of gate-source voltage; typical values

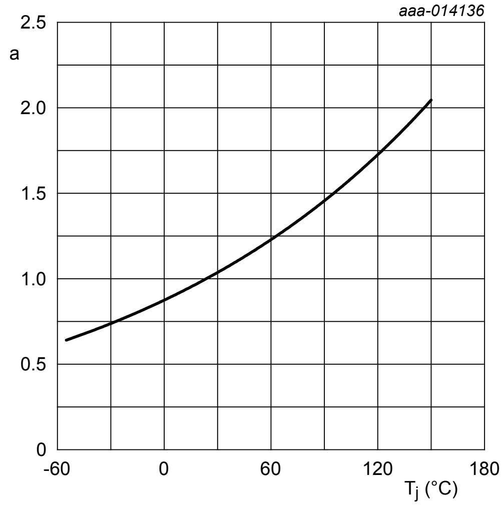
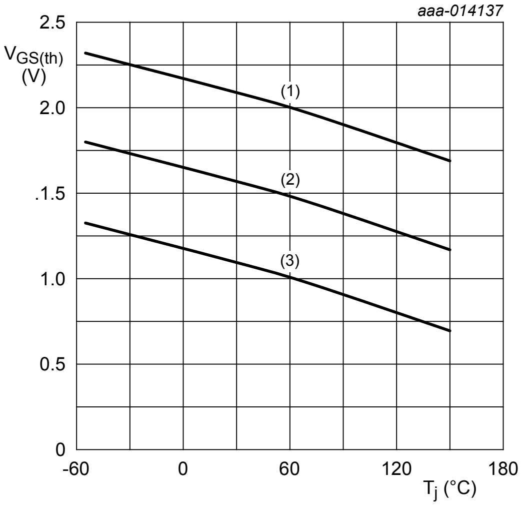


Fig. 12. Normalized drain-source on-state resistance as a function of junction temperature; typical values

$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$



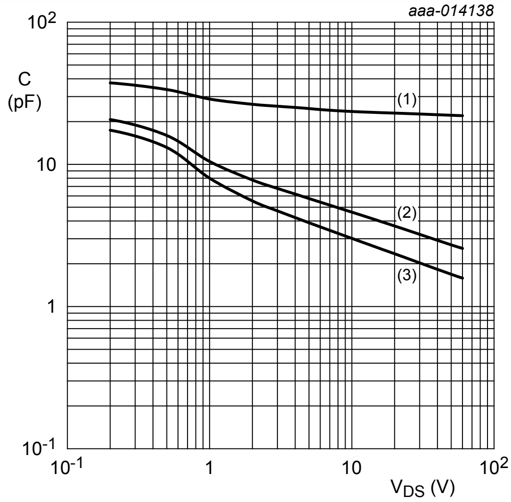
I_D = 0.25 mA; $V_{DS} = V_{GS}$

(1) maximum values

(2) typical values

(3) minimum values

Fig. 13. Gate-source threshold voltage as a function of junction temperature



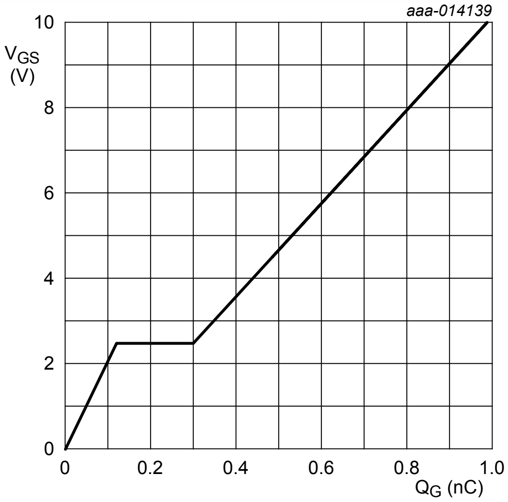
f = 1 MHz; V_{GS} = 0 V

(1) C_{iss}

(2) C_{oss}

(3) C_{rss}

Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



I_D = 0.2 A; V_{DS} = 30 V; T_{amb} = 25 °C

Fig. 15. Gate-source voltage as a function of gate charge; typical values

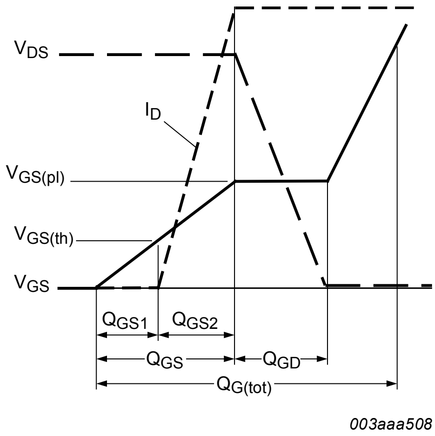
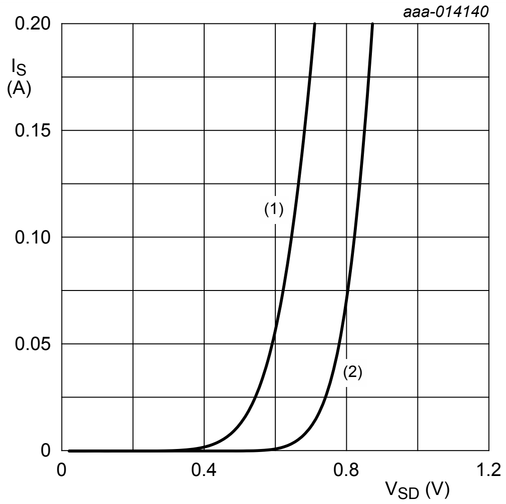


Fig. 16. MOSFET transistor: Gate charge waveform definitions



V_{GS} = 0 V

(1) T_j = 150 °C

(2) T_j = 25 °C

Fig. 17. Source current as a function of source-drain voltage; typical values

11. Test information

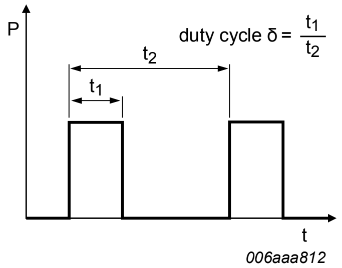
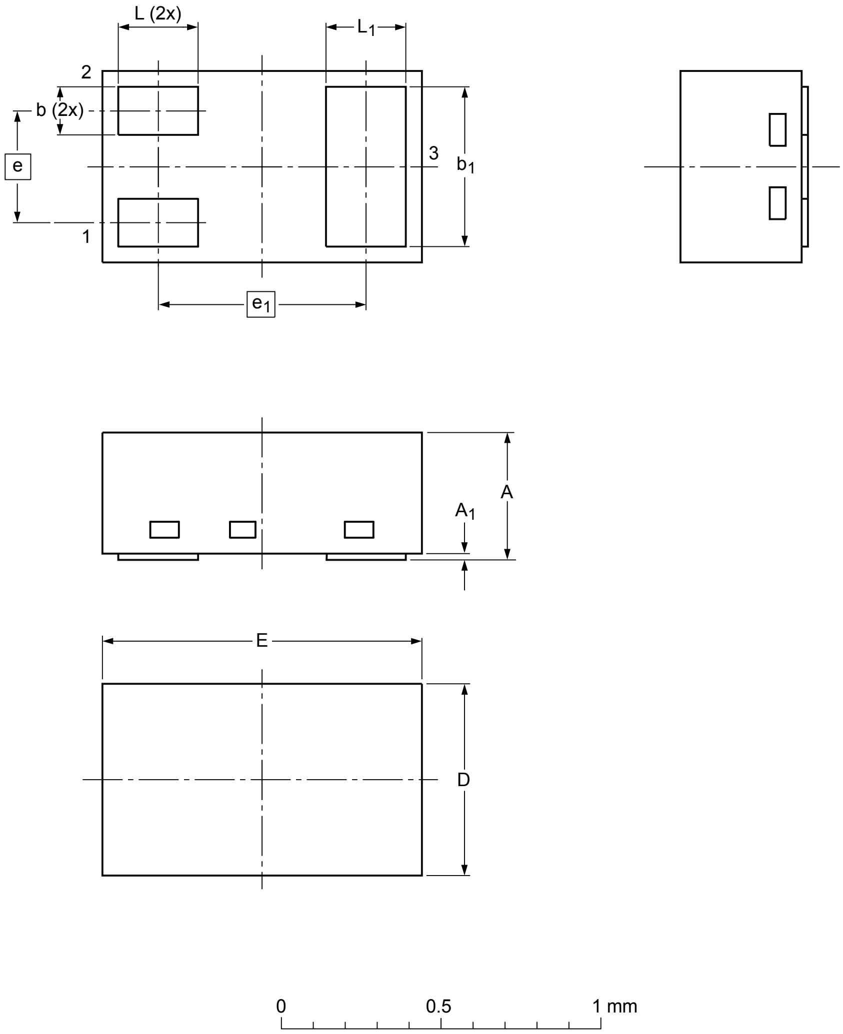


Fig. 18. Duty cycle definition

12. Package outline

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.37 mm **SOT883B**



scale

Dimensions

Unit		A(1)	A1	b	b1	D	E	e	e1	L	L1
mm	max	0.40	0.04	0.20	0.55	0.65	1.05			0.30	0.30
	nom	0.37		0.15	0.50	0.60	1.00	0.35	0.65	0.25	0.25
	min	0.34		0.12	0.47	0.55	0.95			0.22	0.22

Note

1. Including plating thickness

sot883b_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT883B						~~11-11-02~~ 12-01-03

Fig. 19. Package outline DFN1006B-3 (SOT883B)

13. Soldering

Footprint information for reflow soldering **SOT883B**

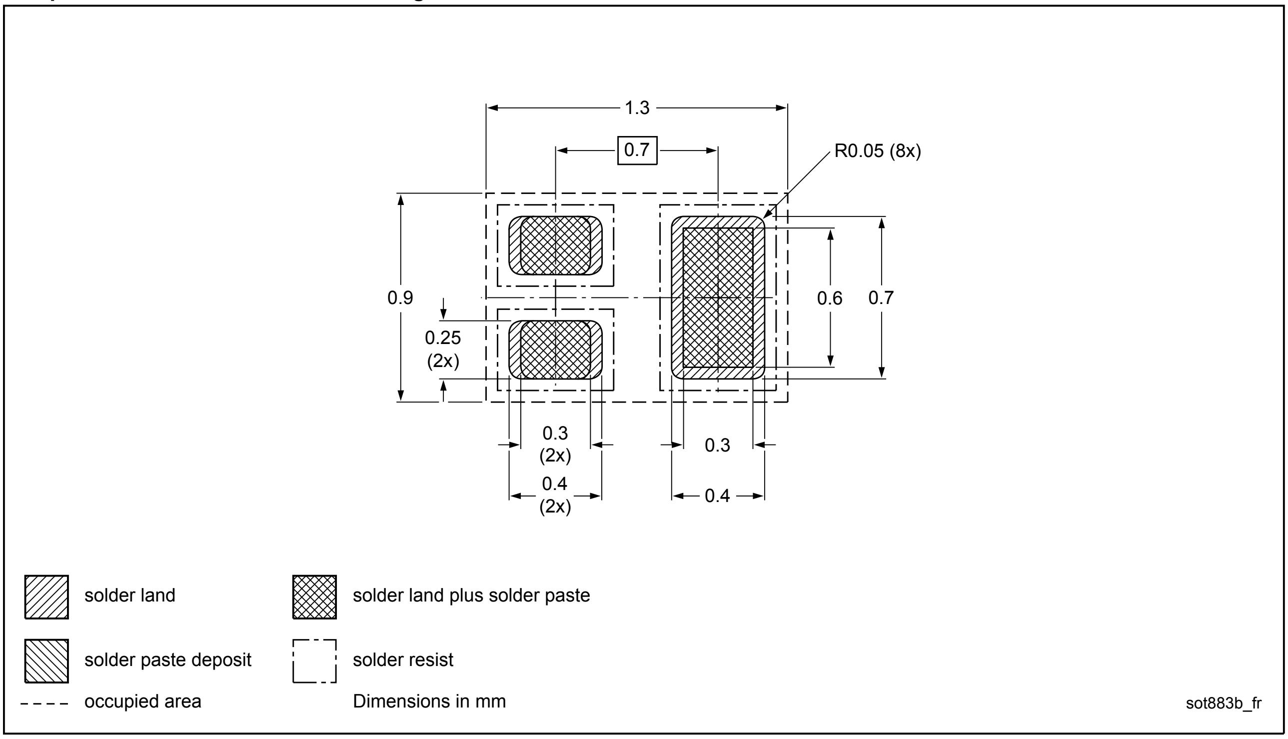


Fig. 20. Reflow soldering footprint for DFN1006B-3 (SOT883B)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
NX7002BKMB v.2	20141203	Product data sheet	-	NX7002BKMB v.1
Modification:	• Figure 3 updated			
NX7002BKMB v.1	20141001	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
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